

ABSTRACT OF THE DISCLOSURE

A stencil for placing conductive elements over pads accessible at a first surface of a microelectronic element includes a main body having a top surface and a bottom surface and a plurality of openings extending between the top and bottom surfaces, the main body being adapted for overlying the first surface of the microelectronic element so that the openings are in substantial alignment with the pads of the microelectronic element. The stencil also includes a spacer element under the bottom surface of the main body, the spacer element being adapted for maintaining the main body above the first surface of the microelectronic element and remote from the pads of the microelectronic element.

270882_1.DOC